

## HOW TO REACH US

# CHEMNITZER SEMINAR SYSTEMS INTEGRATION TECHNOLOGIES

### Registration:

Please send an e-mail for registration to [sabrina.loetsch@enas.fraunhofer.de](mailto:sabrina.loetsch@enas.fraunhofer.de) until June 19, 2015.

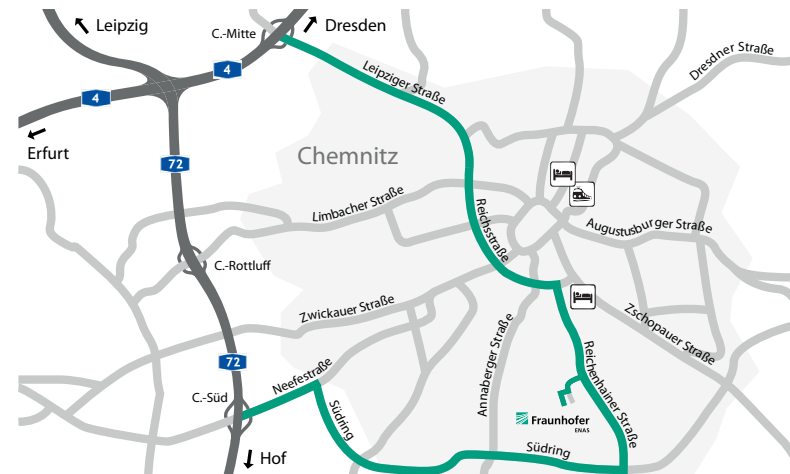
### Hotel:

Sabrina Lötsch will order rooms in Günnewig Hotel Chemnitzer Hof. If you need an accommodation, please contact [sabrina.loetsch@enas.fraunhofer.de](mailto:sabrina.loetsch@enas.fraunhofer.de)

### Contact:

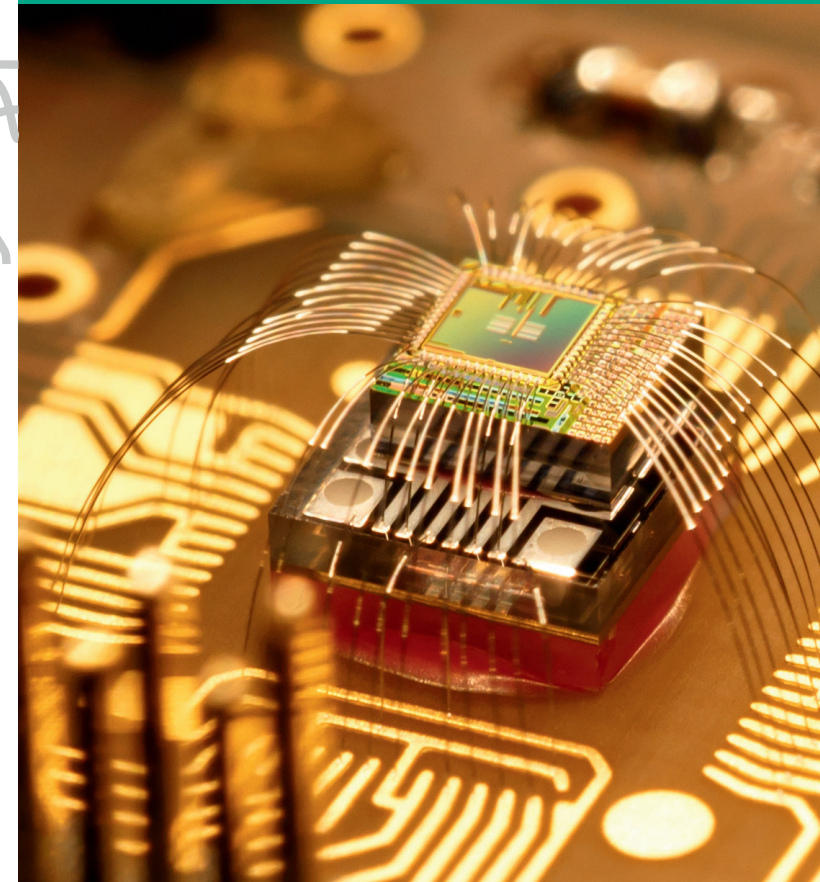
Ms. Sabrina Lötsch  
phone.: +49 371 45001-223  
[sabrina.loetsch@enas.fraunhofer.de](mailto:sabrina.loetsch@enas.fraunhofer.de)

Mr. Mario Baum  
phone.: +49 371 45001-261  
[mario.baum@enas.fraunhofer.de](mailto:mario.baum@enas.fraunhofer.de)



Fraunhofer ENAS  
Technologie-Campus 3, 09126 Chemnitz (Germany)  
(access to Technologie-Campus is possible via Rosenbergstraße  
or Fraunhoferstraße)

phone: +49 371 45001-0  
fax: +49 371 45001-101  
[info@enas.fraunhofer.de](mailto:info@enas.fraunhofer.de)  
[www.enas.fraunhofer.de](http://www.enas.fraunhofer.de)



## AGENDA

TUESDAY  
JUNE 23, 2015

## CHEMNITZER SEMINAR „SYSTEM INTEGRATION TECHNOLOGIES“

Smart systems are becoming more and more important in our daily life, e.g. in cars, efficient energy management, security applications, medical engineering, logistics and other applications.

A major bottleneck, however, to allow these devices to hit the market, is the packaging of the sensitive microstructures to a rugged outer casing that makes handling possible and allow them to withstand even harsh environments. On this path, many unexpected challenges are encountered when interfacing the system structure to the outer world.

The focus of the 22nd Chemnitzer Seminar is to discuss and show paths to solve these challenges.

- 1:00 – 1:20 pm **Packaging of MEMS devices – An overview** | Dr. Maik Wiemer, Fraunhofer ENAS
- 1:20 – 1:55 pm **Open TSV technology for 3D sensor applications** | Jörg Siegert, ams AG
- 1:55 – 2:20 pm **Packaging of integrated photonic devices; applications, user foundry services and design rules** | Dr. Peter O’Brien, University College Cork
- 2:20 – 2:45 pm **Silver sinter interconnects in diversified applications** | Thomas Krebs, Heraeus Deutschland GmbH & Co. KG
- 2:45 – 3:10 pm **16Mpixel 3D stacked CMOS image sensor** | Toru Kondo, Olympus
- 3:10 – 3:40 pm Coffee break
- 3:40 – 4:05 pm **Towards MEMS loudspeaker fabrication by using metallic glass thin films** | Felix Gabler, Fraunhofer ENAS
- 4:05 – 4:30 pm **MEMS packaging – Infinite variety of bonding applications** | Margarete Zoberbier, SUSS MicroTec Lithography GmbH
- 4:30 – 4:55 pm **Passive RFID sensor solutions** | Reinhard Jurisch, Microsensys
- 4:55 – 5:20 pm **Geology needs MEMS and sensors** | Dr. Dieter Rammilmair, Federal Institute for Geosciences and Natural Resources

## AGENDA

WEDNESDAY  
JUNE 24, 2015

- 9:00 – 9:10 am **Welcome** | Dr. Maik Wiemer, Fraunhofer ENAS
- 9:10 – 9:35 am **MEMS-based industry 4.0 applications** | Sven Bochmann, Turck Duotec GmbH
- 9:35 – 10:00 am **Large-area patterning by roller-based nanoimprint lithography** | Dr. Ursula Palfinger, JOANNEUM RESEARCH Forschungsgesellschaft mbH
- 10:00 – 10:25 am **Applications of thermal nano imprint lithography** | Steffi Proschwitz, University of Applied Sciences Zwickau
- 10:25 – 10:55 am Coffee break
- 10:55 – 11:20 am **Oxide free direct wafer bonding** | Dr. Martin Eibelhuber, EV Group
- 11:20 – 11:45 am **Telecardiology – Technical innovations and challenges in clinical practice** | Dr. Axel Müller, Klinikum Chemnitz
- 11:45 – 12:10 pm **Packaging and fabrication opportunities enabled by the room temperature deposition of Parylene** | Marco Haubold, Fraunhofer ENAS
- 12:10 – 12:35 pm **MEMS and biological cells – advances in designing sensors, actuators and biocompatible surfaces for medical use** | Prof. Dr. Richard Funk, Technische Universität Dresden
- 12:35 – 1:00 pm **Thales vision and need in advanced packaging for high end applications** | Michel Brizoux, Thales Global Services